MDA Series

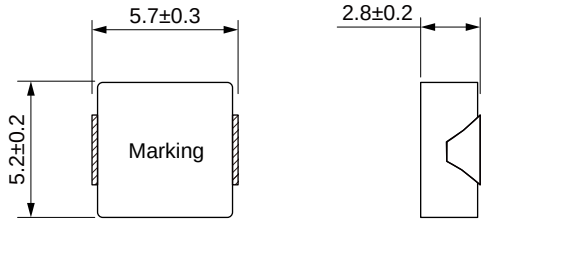
SMD Low Profile High Current Molded Inductor

Size 5030

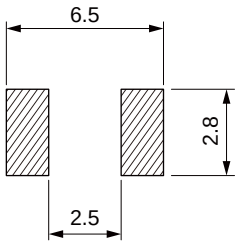
FEATURES

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- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
-
-
-
-
-

Dimensions: [mm]



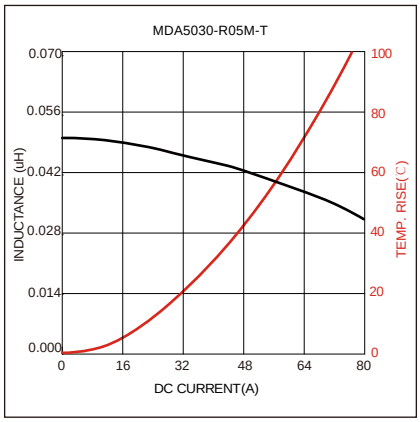
Land Pattern: [mm]

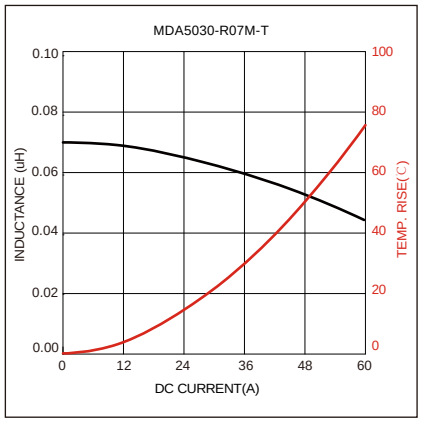


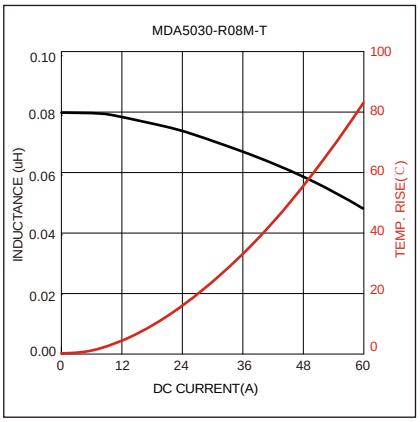
Electrical Properties:

MDA5030-R05M-T	0.05	±20%	46	68	0.57	0.63
MDA5030-R07M-T	0.07	±20%	42	52	0.64	0.71
MDA5030-R08M-T	0.08	±20%	40	50	0.74	0.85

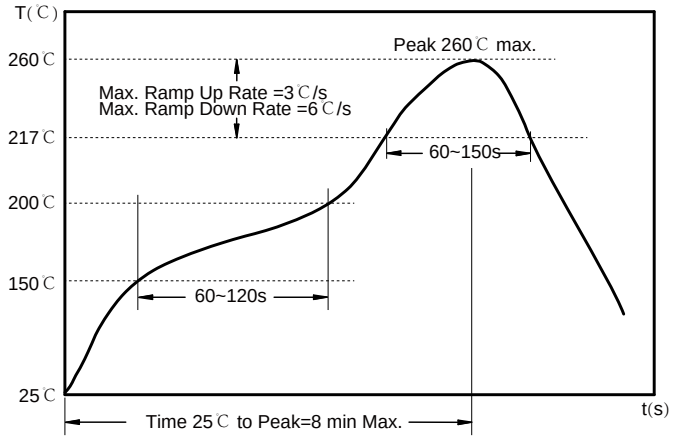
Typical Electrical Characteristics:







Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

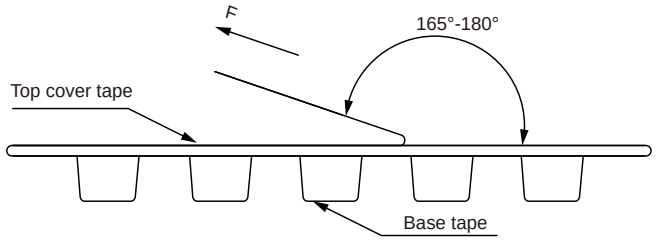
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension:

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA5030-T	5.5 ± 0.1	6.2 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	8.0 ± 0.1	12.0 ± 0.3	3.3 ± 0.1	1.75 ± 0.1	0.35 ± 0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	Printing Inductance+period)

Reel Dimension：[mm]



Packaging Quantity: